

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XCL210xxxxGR-G
Typical mass: 22.0 mg

Part	Part name	Weight(mg)	Material name	Ratio(ppm)	CAS No.
Coil	Core (Ferrite)	11.450	Iron oxide	520500	1309-37-1
		2.257	Zinc oxide	102600	1314-13-2
		2.199	Nickel oxide	99900	1313-99-1
		0.623	Copper oxide	28300	1317-38-0
		0.078	Tin oxide	3500	18282-10-5
	Internal conductor	0.418	Silver	19000	7440-22-4
	Electrode	0.477	Silver	21700	7440-22-4
		0.175	Nickel	8000	7440-02-0
	0.224	Tin	10200	7440-31-5	
Adhesive Resin	Adhesive Resin	0.045	Epoxy resin	2000	-
		0.035	Silica	1600	14808-60-7
		0.010	Organic filler	500	-
		0.010	Inorganic filler	500	-
IC	Silicon chip	0.466	Silicon	21200	7440-21-3
			- Arsenic	<1	7440-38-2
	Lead pad	1.298	Nickel	59000	7440-02-0
		0.123	Silver	5600	7440-22-4
		0.014	Gold	700	7440-57-5
	Die attach	0.022	Epoxy resin	1000	-
		0.016	Acrylic resin	700	-
	Bonding wire	0.083	Gold	3800	7440-57-5
	Resin	1.479	Silica	67200	60676-86-0
	0.174	Epoxy resin	7900	-	
	0.183	Phenol resin	8300	-	
	0.141	Metal hydroxide	6400	-	

- * The component composition is based on the information provided by raw material vender.
- * The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.
- * Any indication "-" in CAS number means "confidential."